
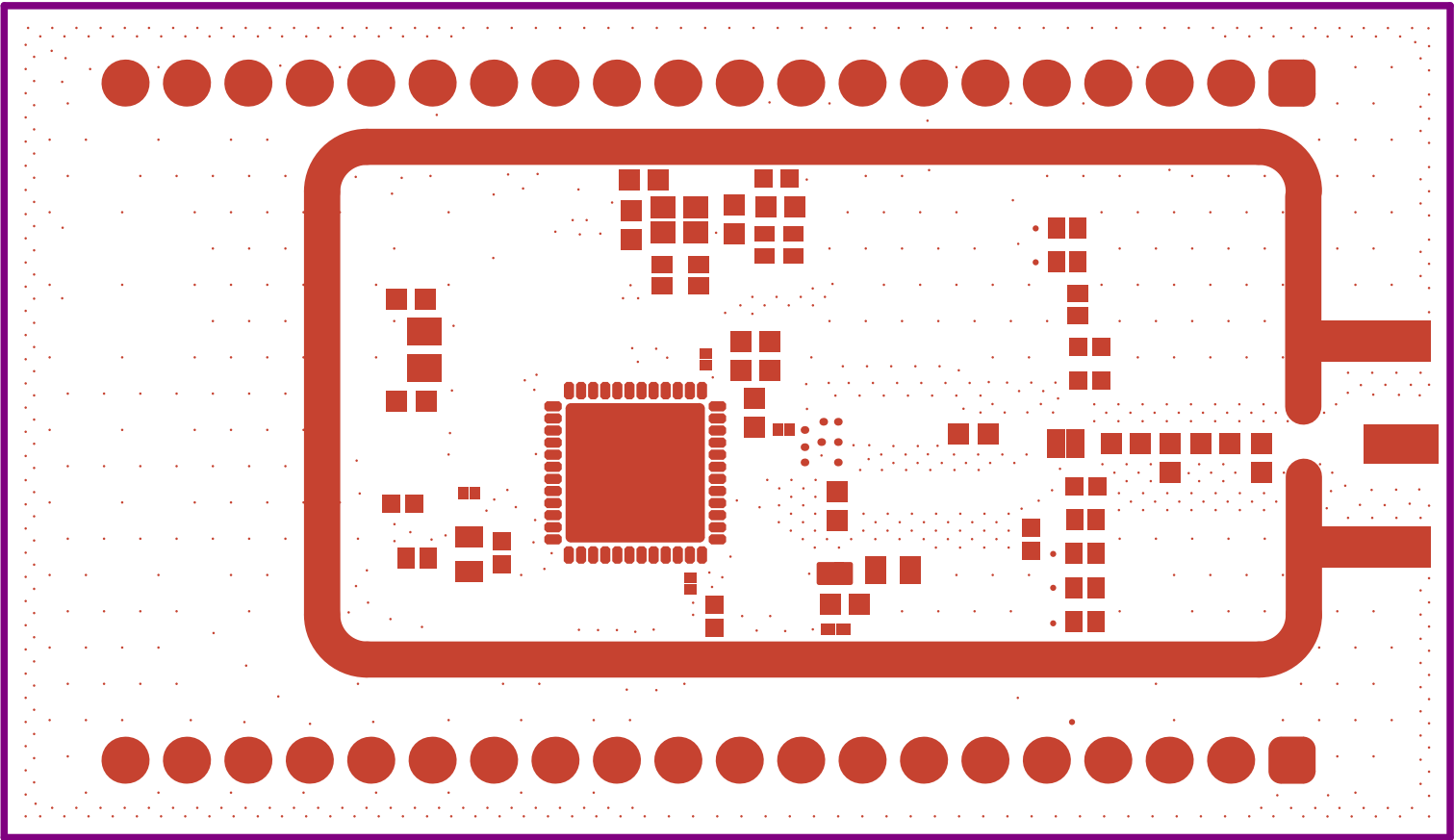

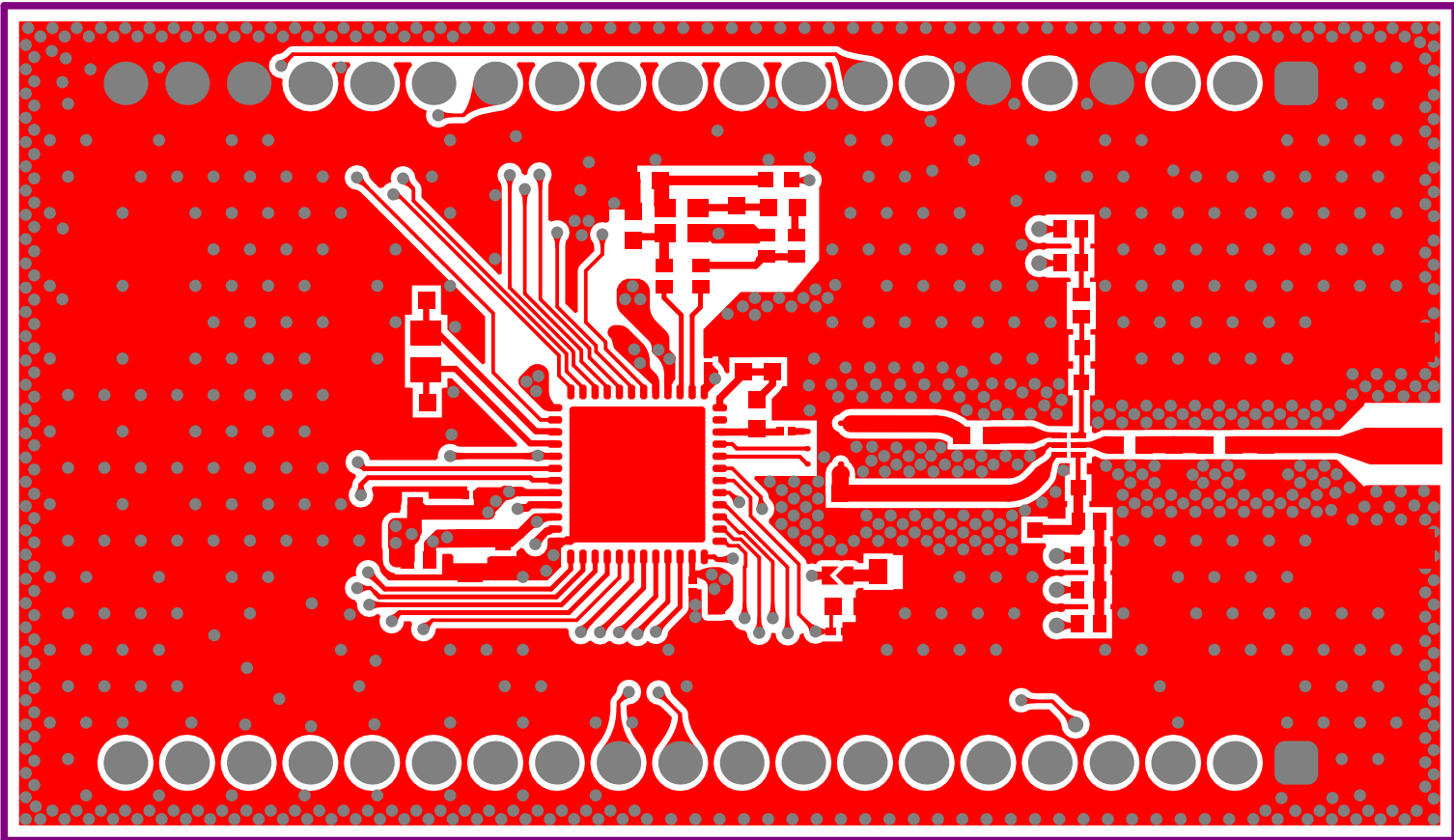



Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	

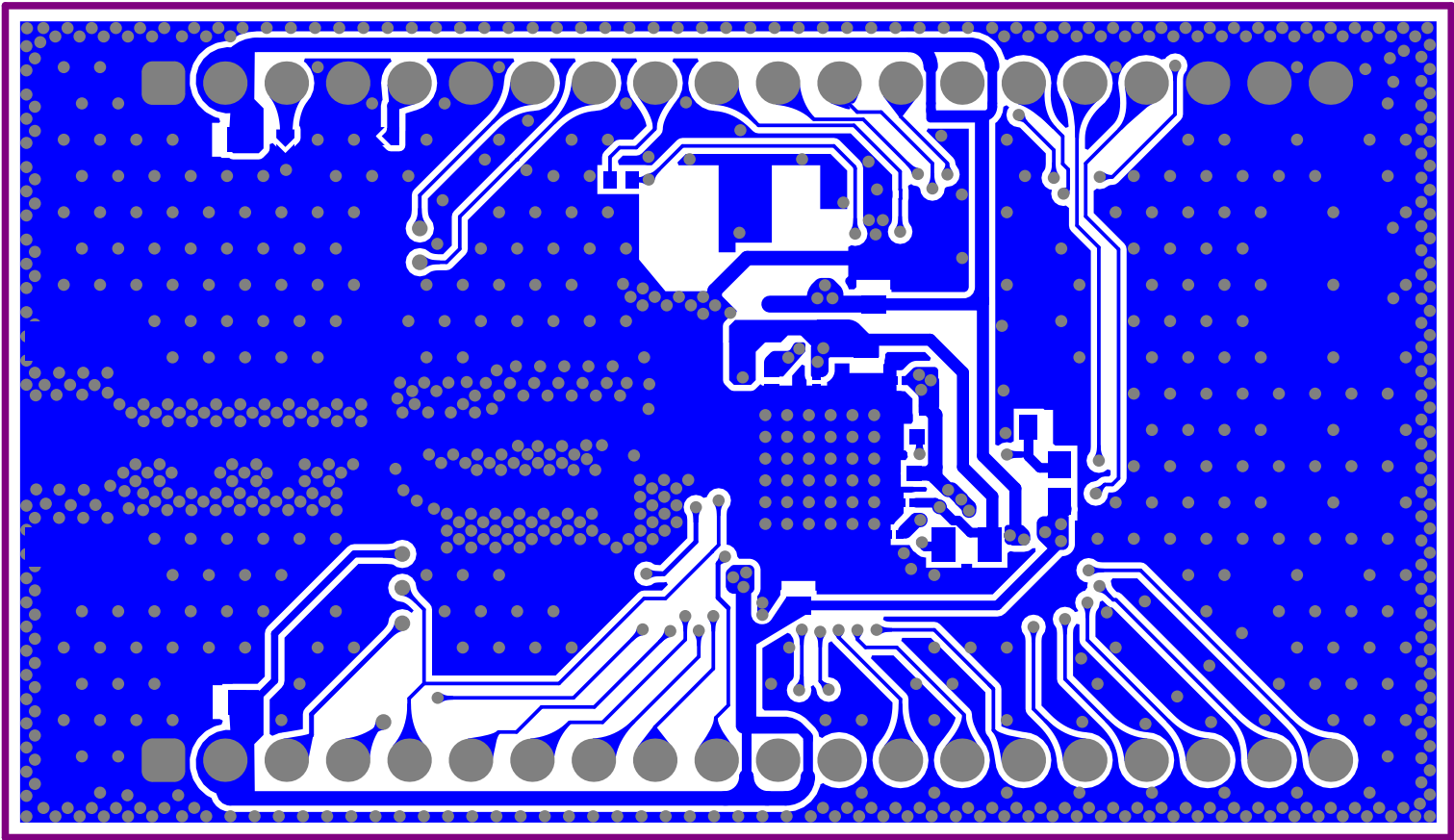



Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	

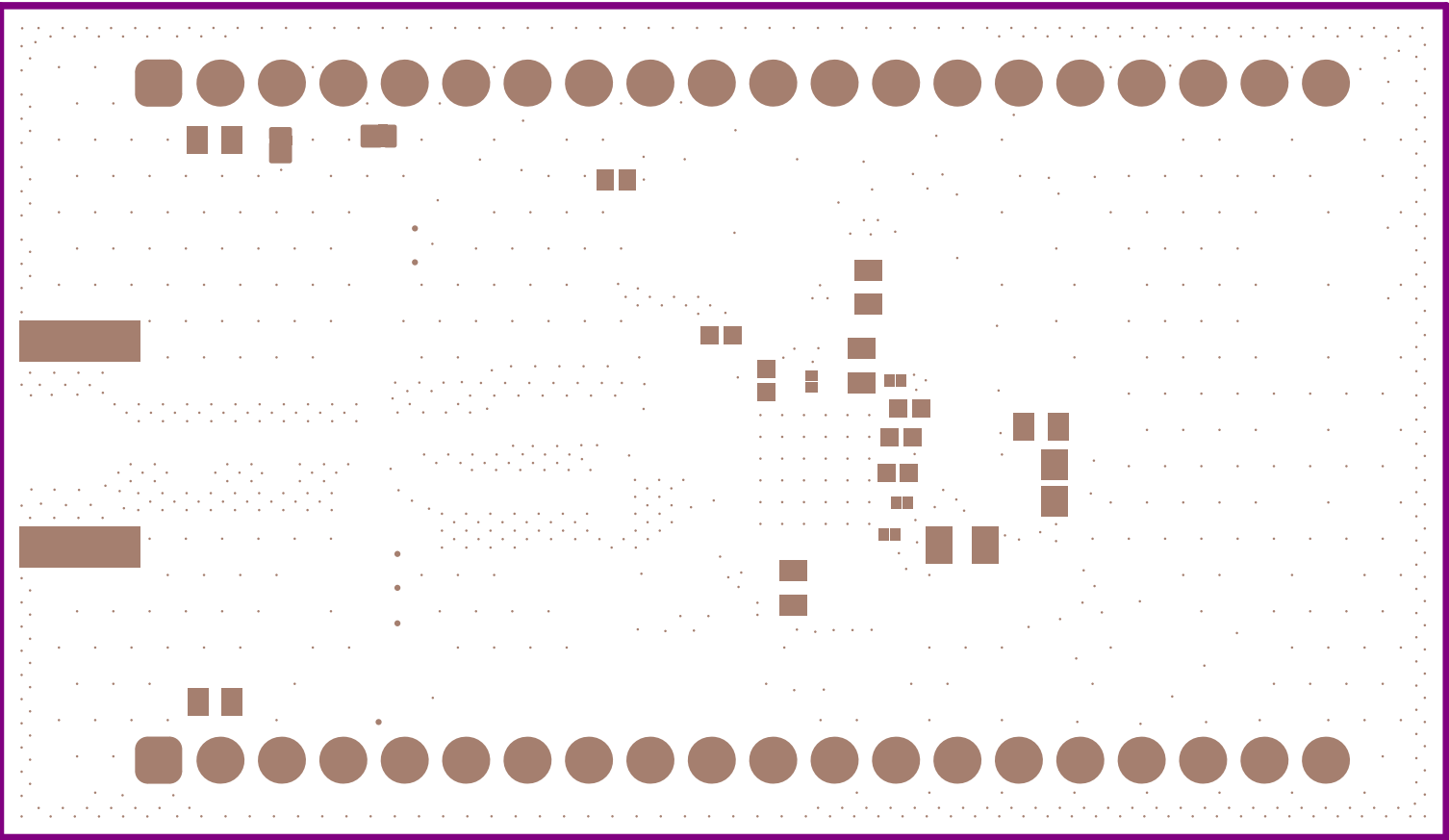



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	1.18mil	3.5
1	Top Layer		1.38mil	
	Dielectric 1	FR-4	27.95mil	5
2	Bottom Layer		1.38mil	
	Bottom Solder	Solder Resist	1.18mil	3.5
	Bottom Overlay			

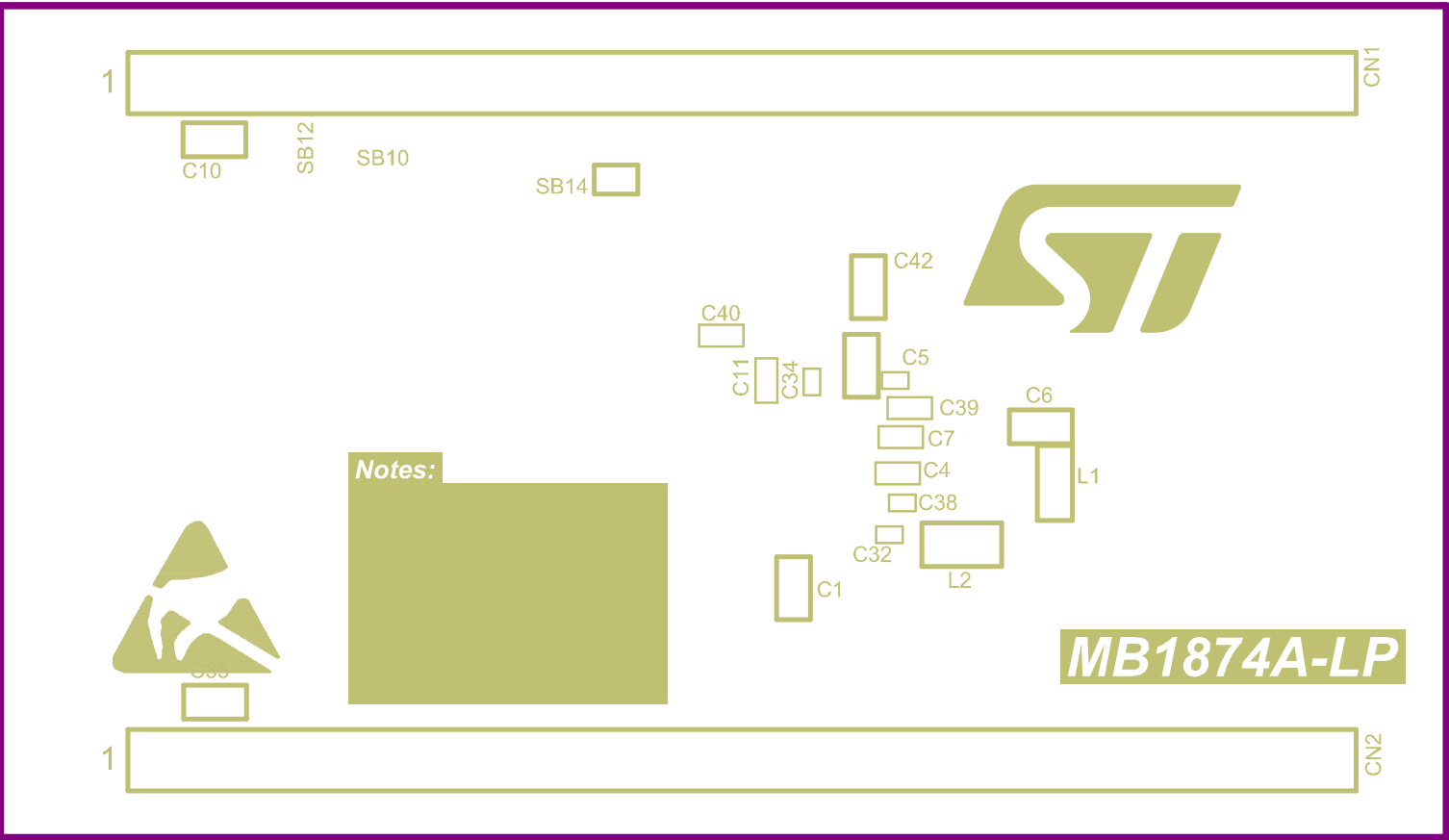
Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	




Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	



Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	



Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
▽	941	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
□	40	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
	981 Total							

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4☒TG-170☐TG-150☐TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒GREEN☐BLUE☐RED☐BLACK

D. SILKSCREEN COLOR :

☒WHITE☐YELLOW☐BLACK

E. SURFACE FINISH :

☒ENIG☐IMMERSION SILVER☐IMMERSION TIN
☐HASL☐HASL (PB-FREE)☐GOLDEN FINGER

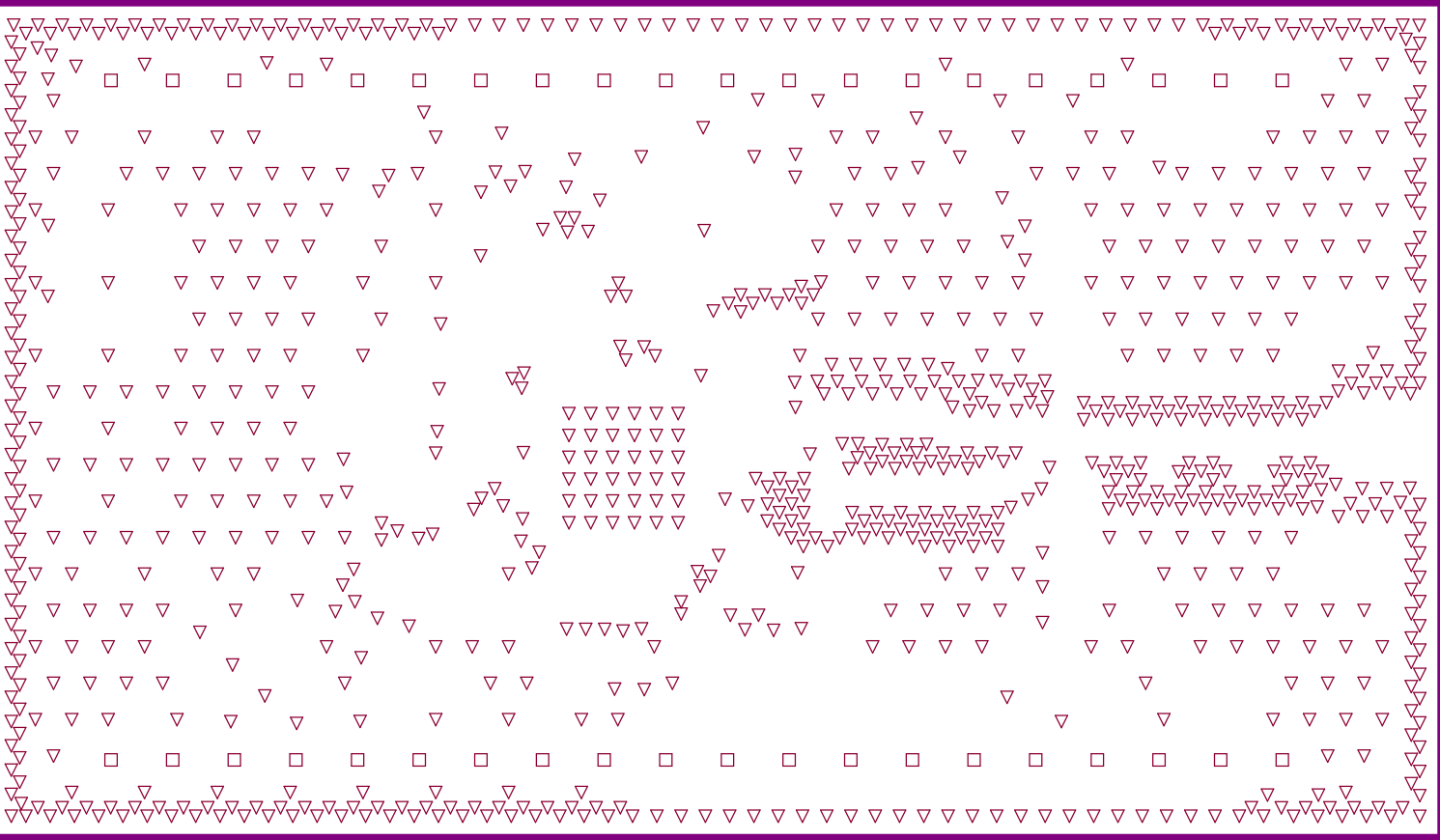
☐IMPEDANCE CONTROL :
☐NO☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)


G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒SOLDERMASK☐NON-CONDUCTIVE EPOXY.

☐STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_IPD_2Layers_LowPower		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1874_LP	
Date: 20/07/2022	Rev: A	

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	27.56	9.84	50 ohm	NA	+/- 10%